SET-1 Code No: R2032042

## III B. Tech II Semester Regular Examinations, July -2023 **VLSI DESIGN**

(Electronics and Communication Engineering)

Time: 3 hours Max. Marks: 70

#### Answer any FIVE Questions ONE Question from Each unit All Questions Carry Equal Marks \*\*\*\* **UNIT-I** 1. a) With a neat sketch explain BICMOS fabrication in p-well process and also [7M] explain its operation. b) Write down the equations for Ids of an n-channel enhancement MOSFET [7M] operating in Non-saturated region and saturated region. (OR) Explain the PMOS enhancement mode fabrication process for different conditions [7M] of Vds? b) An NMOS transistor is operating in active region with the following parameters: [7M] VGS=3.9V, Vtn=1V, W/L=100, $\mu$ nCox=90 $\mu$ A/V<sup>2</sup>. Find I<sub>D</sub> and R<sub>DS</sub>. **UNIT-II** Explain the problem of driving large capacitive loads? How such loads can be [7M] driven? b) Discuss the limits of scaling. Why scaling is necessary for VLSI circuits? [7M] 4. a) Explain about static, dynamic and domino logics with examples. [7M] b) How does depletion regions around source and drain are affected due to scaling [7M] down of device dimensions? Explain **UNIT-III** 5. a) Draw the circuit diagram of single stage amplifier with resistive load and explain [7M] its operation. b) Explain the importance of body bias effect of a MOSFET in detail. [7M] 6. a) Draw the circuit diagram of Common Drain amplifier and explain its operation. [7M] b) Write short notes on Modeling of transistor in detail. [7M] **UNIT-IV** 7. a) Explain the operation of multiplexer based latches in detail. [7M] b) Write short notes on Meta stability in CMOS Logic. [7M] (OR) 8. a) Draw the circuit diagram of SR Master Slave register and explain its operation. [7M] b) Write short notes on Ultra Deep-Submicron Era in detail. [7M] 9. a) Write about FPGA Programming Technologies in detail. [7M] b) Explain the step by step approach of FPGA design process on Xilinx [7M] environment. (OR) 10. a) Draw and explain the routing architecture of field programmable gate arrays. [7M]

[7M]

b) Write about the shift register design and implementation onto FPGA.

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SET-2

## III B. Tech II Semester Regular Examinations, July -2023 **VLSI DESIGN**

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Time: 3 hours Max. Marks: 70

# Answer any FIVE Questions ONE Question from Each unit

All Questions Carry Equal Marks
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		<u>UNIT-I</u>	
1.	a)	Give the steps for single metal CMOS n-well process and additional steps for bipolar devices.	[7M]
	b)	Explain how the Bi-CMOS inverter performance can be improved. (OR)	[7M]
2.	a)	Determine pull-up to pull-down ratio of an NMOS inverter when driven through one or more pass transistors.	[7M]
	b)	Design a stick diagram for CMOS logic $Y = (A+B+C)^{\prime}$ .	[7M]
		<u>UNIT-II</u>	
3.	a)	Discuss about NMOS transistor as a switch and PMOS transistor as a switch.	[7M]
	b)	Discuss the inverter delay and propagation delay.	[7M]
		(OR)	
4.	a)	Define scaling factor? Explain different types of device parameters.	[7M]
	b)	Two NMOS inverters are cascaded to drive a capacitive load CL=16Cg.	[7M]
		Calculate pair delay Vin to Vout in terms of $\tau$	
		<u>UNIT-III</u>	
5.	a)	Draw the circuit diagram of Common Gate amplifier and explain its operation.	[7M]
	b)	Explain the operation of MOSFET along with characteristics.	[7M]
		(OR)	
6.	a)	Explain the operation of single stage amplifier with diode connected load along with diagram.	[7M]
	b)	Write short notes on Modeling of transistor in detail.	[7M]
		UNIT-IV	
7.	a)	Explain the operation of Master-Slave Based Edge Triggered Register along with diagram.	[7M]
	b)	Write short notes on Cascading Dynamic Gates in detail. (OR)	[7M]
8.	a)	Draw and explain the operation of Clocked CMOS register in detail.	[7M]
	b)	Write short notes on Complementary CMOS Logic in detail.	[7M]
		<u>UNIT-V</u>	
9.	a)	Write about Programmable I/O blocks in FPGAs.	[7M]
	b)	Explain about different programmable elements in FPGA architectures.	[7M]
		(OR)	
10.	a)	Explain the concept of Short channel effects in detail.	[7M]
	b)	Write the steps involved to prototype the HDL code onto FPGA device.	[7M]

SET-3 Code No: R2032042

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(Electronics and Communication Engineering)

Time: 3 hours Max. Marks: 70

## Answer any FIVE Questions ONE Question from Each unit All Questions Carry Equal Marks

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Explain	the	steps	in	twin-tub	process	of	CMOS	fabrication	with	suitable	[7M]
sketch.											

[7M]

What are the advantages of BICMOS process over CMOS technology? b) [7M] (OR)

**UNIT-I** 

2. Explain 2 µm Double Metal, Double Poly CMOS / Bi-CMOS Rules. [7M] a)

b) Draw the circuit for NMOS inverter and explain its operation and [7M] characteristics.

#### **UNIT-II**

3. What is meant by sheet resistance Rs? Explain the concept of Rs applied to [7M] MOS transistors.

Calculate on resistance of an inverter from VDD to GND. If n- channel sheet b) [7M] resistance  $R_{sn}=10^4\Omega$  per square and P-channel sheet resistance  $R_{sp}=3.5\times10^4$  $\Omega$  per square.(Zpu=4:4 and Zpd=2:2)

4. What are the alternate gate circuits are available? Explain any one of item with [7M] a) suitable sketch.

b) Write about the scaling limitations due to sub Supply voltages in MOSFETS. [7M]

### UNIT-III

5. a) List out different biasing styles of MOSFET and explain. [7M]

b) List out advantages of Common Source amplifier in detail. [7M]

6. Explain the operation of Common Gate amplifier along with diagram. a) [7M]

b) What is the term current sources and sinks and explain. [7M]

#### **UNIT-IV**

7. What are the Issues in Dynamic Design and explain. a)

[7M] b) Draw the circuit diagram of Clocked CMOS register and explain. [7M]

(OR)

8. Draw the circuit diagram of Cross coupled NAND gates and explain. a) [7M]

b) Explain the term setup time and hold time. [7M]

#### **UNIT-V**

9. What is the need of a FPGA? And write its applications. a)

b) Explain the basic architecture of FPGA along with diagram. [7M]

10. Write about FPGA families of different vendors. a) [7M]

b) Write short notes on Metal Gate Technology in detail. [7M]

1.

a)

SET-4 **R20** Code No: R2032042

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# Answer any FIVE Questions ONE Question from Each unit All Questions Carry Equal Marks \*\*\*\*\*

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		UNIT-I	
1.	a)	What are the steps involved in the nMOS fabrication? Explain with neat sketches.	[7M]
	b)	List out few Comparison between CMOS and Bi-CMOS technology in detail. (OR)	[7M]
2.	a)	Explain and derive the expressions for MOS transistor parameters gm, gds and $\omega 0$ .	[7M]
	b)	Distinguish between nMos,pMos and CMOS fabrication process.	[7M]
3.	a)	What are the limits on logic levels and supply voltage due to noise in scaling?	[7M]
	b)	What is inverter delay? How delay is calculated to for multiple stages?  (OR)	[7M]
4.	a)	Describe three sources of wiring capacitances. Explain the effect of wiring capacitance on the performance of a VLSI circuit.	[7M]
	b)	Explain scaling of MOS circuits. Give merits and demerits of scaling.	[7M]
5.	a)	UNIT-III  Draw and explain the operation of Common Source amplifier.	[7M]
	b)	Draw the circuit diagram of single stage amplifier with resistive load and explain its operation.	[7M]
		(OR)	
6.		Explain the following terms in detail (a) body bias effect (b) biasing styles UNIT-IV	[14M]
7.	a) b)	Draw the circuit diagram of SR Master Slave register and explain its operation. Write short notes on pipelining.  (OR)	[7M] [7M]
8.	a)	Explain the importance of Pass-Transistor Logic along with example.	[7M]
	b)	How to find the Power Dissipation of Dynamic Logic and explain.  UNIT-V	[7M]
9.	a)	Explain the FPGA design flow in detail.	[7M]
	b)	Compare Full-Custom design with semi-custom design. (OR)	[7M]
10.		Explain the following terms in detail (a) Fin-FET (b)TFET	[14M]